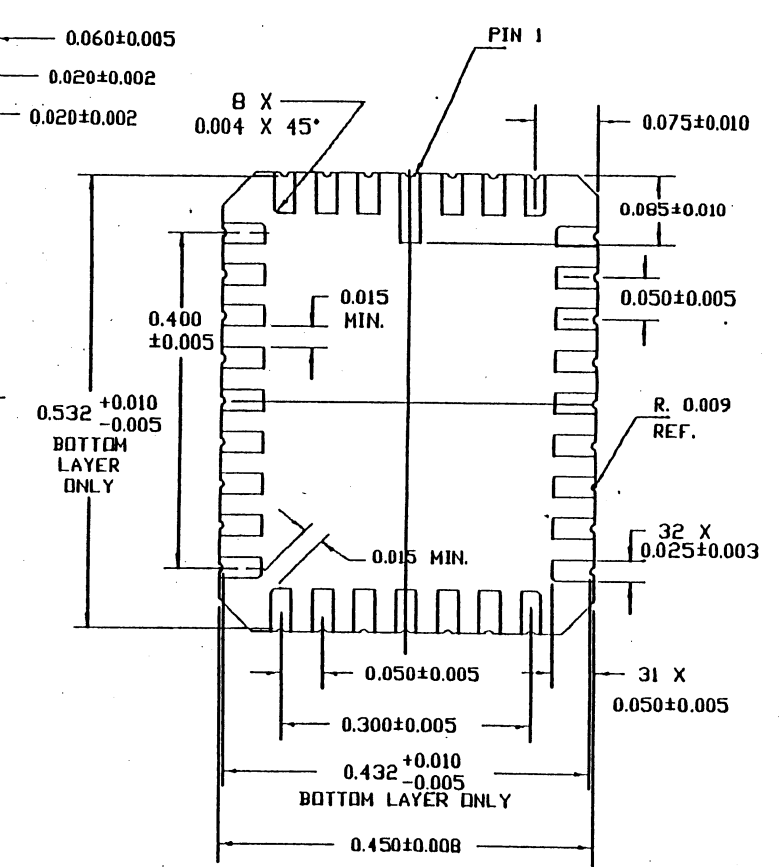
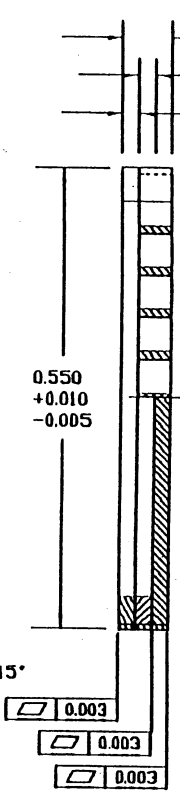
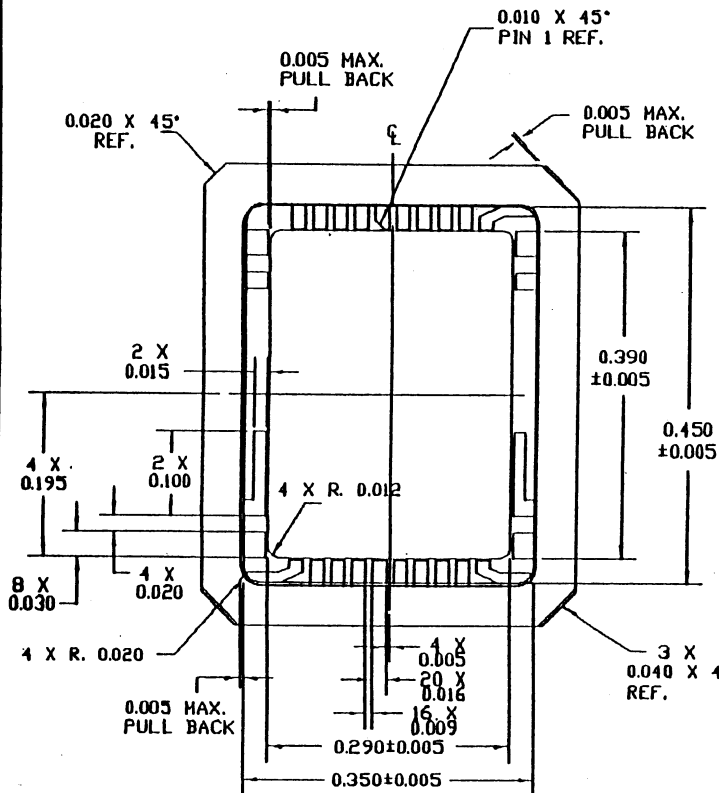


# SSM P/N LCC03209

## NOTES

1. INTERPRET DRAWING PER DOD-STD-100.
2. DIMENSIONS ARE TYPICAL FOR ALL QUADRANTS UNLESS OTHERWISE SPECIFIED.
3. FINISH: GOLD PLATE 80μ DIES MIN OVER 60μ DIES MIN UNDER.
4. DIE ATTACH CAVITY AND SEAL RING WILL BE ELECTRICALLY ISOLATED.
5. LEAD RESISTANCE: 400 MΩ MAX.
6. NO METAL IN DPA CAVITY.

REVISIONS					
ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	MR	611	NEW RELEASE	11/04/93	
	MA	634	CORRECT NOTE #7 (TYPING ERROR)	03/01/94	
	MB	699	CHG NOTE #5	03/14/94	



EXT PIN	BOND PAD	EXT PIN	BOND PAD	EXT PIN	BOND PAD	EXT PIN	BOND PAD
1	1	9	9	17	15	25	21
2	2	10	10	18	N/C	26	22
3	3	11	N/C	19	16	27	23
4	4	12	11	20	17	28	24
5	5	13	12	21	18	29	25
6	6	14	13	22	19	30	26
7	7	15	N/C	23	N/C	31	27
8	8	16	14	24	20	32	28

UNLESS OTHERWISE SPECIFIED		DESIGNED BY	DATE
ALL DIMENSIONS ARE IN INCHES		HTM	03/14/94
FINISH: SEE NOTE 3		APPROVED BY	
MATERIAL			
TITLE		LCC03209	
PART NO.		32 LD LCC - 290 X 390	
SIZE	C	REV	MB
SCALE	10:1	SHEET 1 OF 1	

